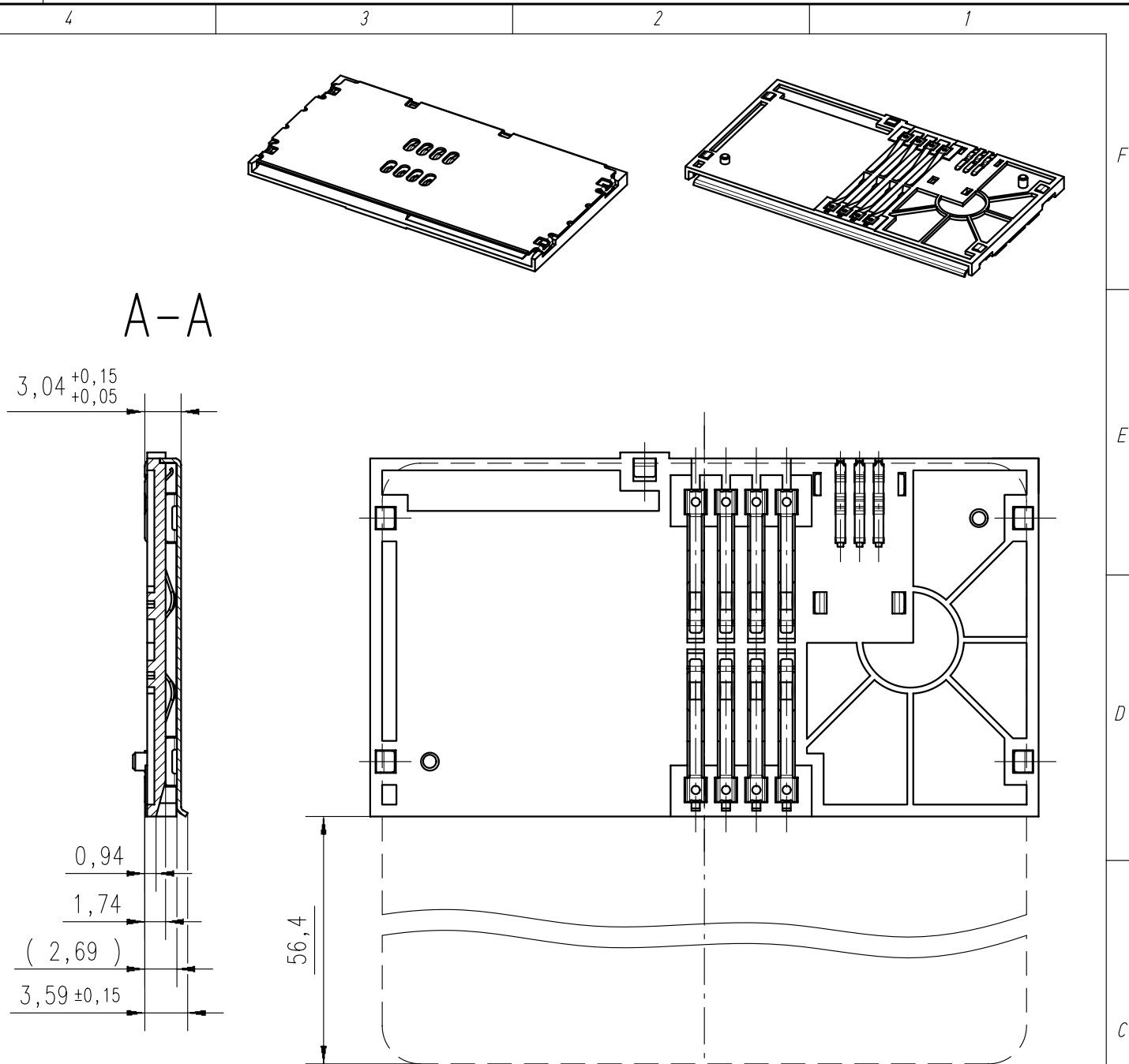
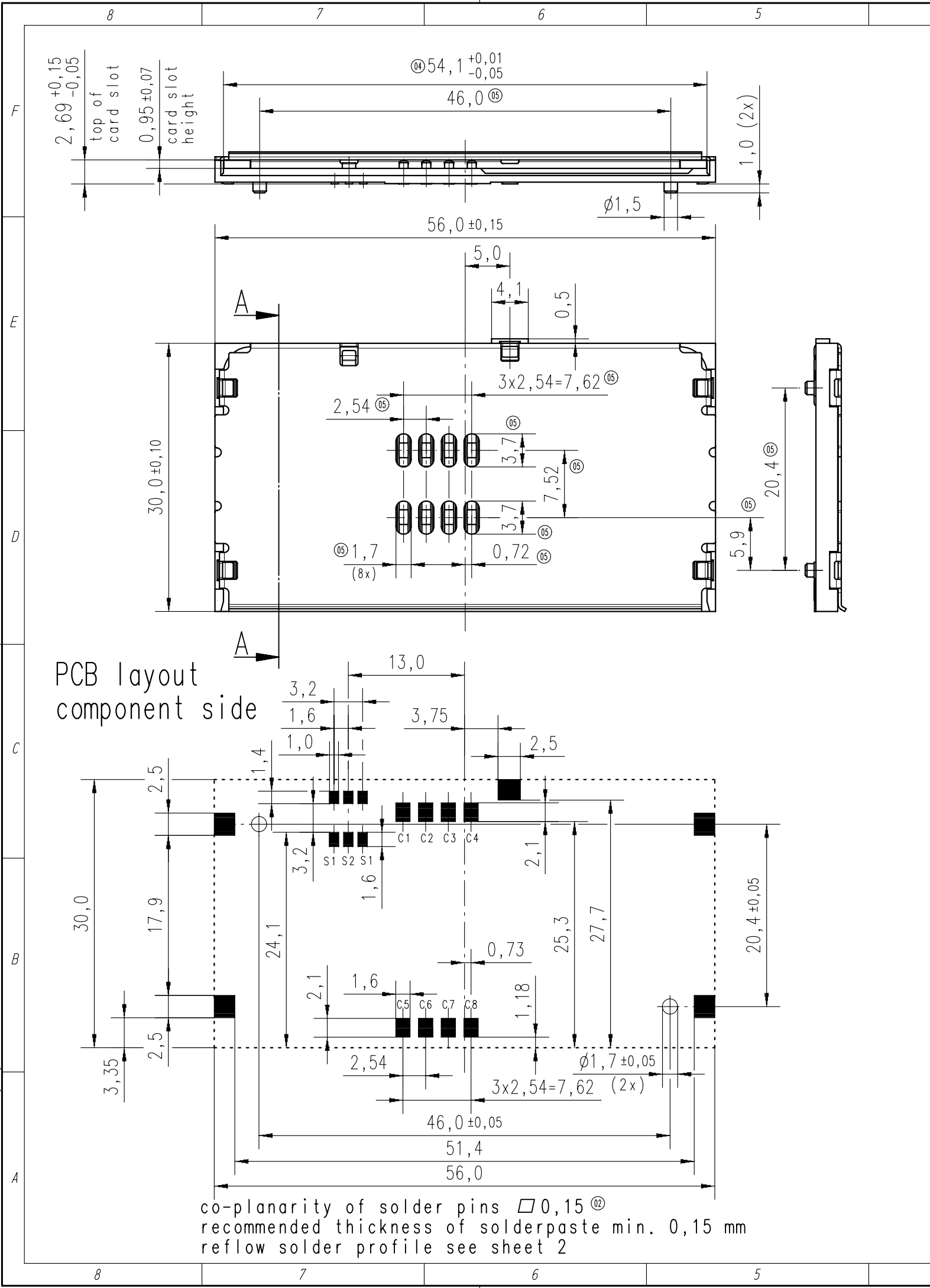


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Im ungelöteten Zustand keine Karte stecken[®]
 Don't insert a card in unsoldered condition

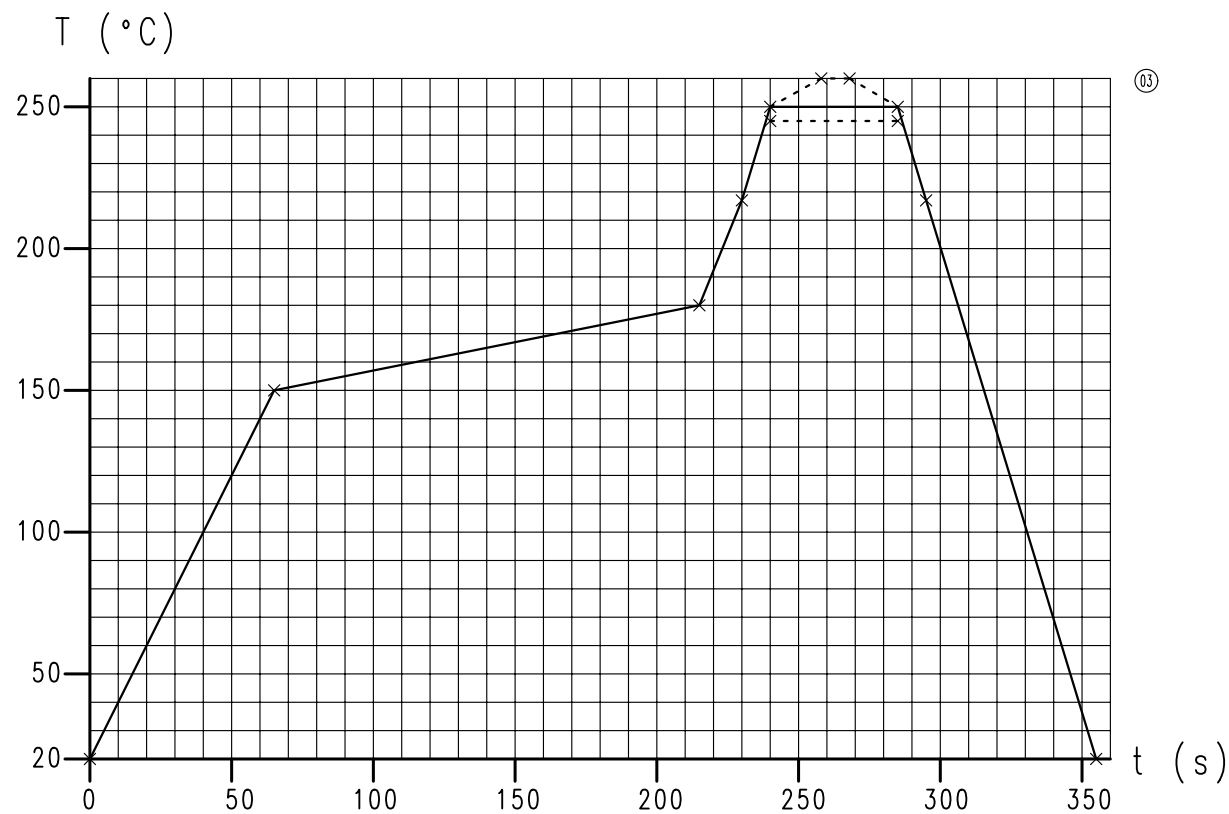
Gewicht (errechnet) / Calc WT: 7,8 9		Zul. Abw. / Tolerances:		Maßstab / Scale 2:1		A3	
Prüfmaß / Testdimension		ISO 2768-mH		DIN 6784		CUSTOMER DRAWING	
Teileindex Partindexnumber		06		Datum / Date		Name	
		Gez.		20.09.		Bertsch	
		Drawn					
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05 201000616 15.09.10 Ber.		03 200800035 17.01.08 Ber.		Amphenol-Tuchel		Blatt / Sheet	
04 200800111 13.02.08 Tol.		02 200700425 21.06.07 Ber.		Electronics GmbH		1	
01 200600185 20.09.06 Ber.						2 Bl.	
Index Änderung / Description Datum / Date Name						Ers. f. / Similar to:	

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estimated temperature profile for lead free soldering^{02 03}

Sn (3,0-4,0)Ag (0,5-0,9)Cu solder alloy



Parameter	Specification
Average temperature gradient in preheating	2,5 °C/s
Preheating temperature	150 °C - 200 °C
Soak time	120 s - 180 s
Time above 217 °C	40 s - 120 s
Peak temperature in reflow	245 °C - 260 °C ⁰³
Time at peak temperature	10 s - 50 s
Temperature gradient in cooling	max -5 °C/s

Specification⁰²

DESIGN

type: push-pull, wiping contacts
normally open switch
with positioning studs

GENERAL CHARACTERISTICS

number of contacts: 8 contacts
switch: normally open (no card inserted)
card type: according to ISO 7810 / 7816
card thickness: 0,76 ±0,08 mm
termination: SMT

MATERIALS AND PLATING

insulator: LCP, black
contact plating: Au over Ni

CLIMATIC CHARACTERISTICS

operating temperature: -25 °C to +70 °C
storage temperature: -40 °C to +85 °C
soldering process: reflow soldering

ELECTRICAL CHARACTERISTICS

contact resistance: max. 100 mΩ (data contacts)
max. 1 Ω (switch)
insulation resistance: >10⁹ Ω
high voltage resistance: 500 V AC for 1 minute
rated voltage: <15 V DC
rated current: <1 A

MECHANICAL CHARACTERISTICS

card insertion force: <10 N
card extraction force: >1 N
mechanical lifetime: 100.000 mating cycles
(without corrosion stress)

PACKAGING

packaging: 32 parts per tray
24 trays per carton

Gewicht (errechnet)/ Calc WT: 7,8 g		Zul. Abw./Tolerances:		Maßstab/Scale 2:1		A3			
Prüfmaß/Testdimension		ISO 2768-mH				CUSTOMER DRAWING			
Teileindex Part index number		06		Datum/Date		Name		Smart Card Connector	
		Gez.		20.09.		Bertsch		SMT with normally open switch	
05 201000616		15.09.10		Ber.					
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03 200800035		17.01.08		Ber.					
02 200700425		21.06.07		Ber.					
01 200600185		20.09.06		Ber.					
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								Blatt/Sheet 2 Bl.	
								Ers. f./Similar to:	